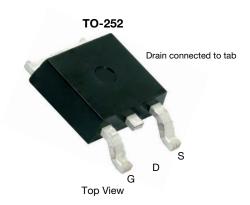


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Vishay Siliconix

# Automotive P-Channel 30 V (D-S) 175 °C MOSFET

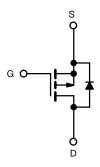


PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-30				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.00320				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.00520				
I <sub>D</sub> (A)	-100				
Configuration	Single				
Package	TO-252				

#### **FEATURES**

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R<sub>g</sub> and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		$V_{DS}$	-30			
Gate-source voltage		$V_{GS}$	± 20	V		
Continuous drain current	T <sub>C</sub> = 25 °C <sup>a</sup>	I-	-100			
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	-94			
Continuous source current (diode conduction	I <sub>S</sub>	-100	Α			
Pulsed drain current <sup>b</sup>	$I_{DM}$	-300				
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	-41			
Single pulse avalanche energy	L = 0.1 IIII1	E <sub>AS</sub>	84	mJ		
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	Pn	136	W		
	T <sub>C</sub> = 125 °C	רט	45	VV		
Operating junction and storage temperature r	$T_J$ , $T_{stg}$	-55 to +175	°C			

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-ambient	PCB mount c	R <sub>thJA</sub>	50	°C/W		
Junction-to-case (drain)		R <sub>thJC</sub>	1.1	G/VV		

### Notes

- a. Package limited
- b. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%$
- c. When mounted on 1" square PCB (FR4 material)



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							I
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-30	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1.5	-2.0	-2.5	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = -30 V	-	-	-1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -30 V, T <sub>J</sub> = 125 °C	-	-	-50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -30 V, T <sub>J</sub> = 175 °C	-	-	-250	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	$V_{DS} \ge -5 \text{ V}$	-50	-	-	Α
	, ,	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -30 A	ı	0.00263	0.00320	
<b>D</b>	5	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -30 A, T <sub>J</sub> = 125 °C	-	-	0.00438	-
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -30 A, T <sub>J</sub> = 175 °C	-	-	0.00502	Ω
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -25 A	-	0.00425	0.00520	
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> :	= -15 V, I <sub>D</sub> = 30 A	-	98	-	S
Dynamic <sup>b</sup>		1					
Input capacitance	C <sub>iss</sub>		V <sub>DS</sub> = -25 V, f = 1 MHz	-	11 085	15 000	pF
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	1342	1900	
Reverse transfer capacitance	C <sub>rss</sub>			-	1181	1600	
Total Gate Charge c	Qq			-	186	280	
Gate-source charge c	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$V_{DS} = -15 \text{ V}, I_{D} = -100 \text{ A}$	-	28	-	nC
Gate-drain charge <sup>c</sup>	Q <sub>qd</sub>			-	28	-	
Gate resistance	R <sub>q</sub>	f = 1 MHz		1.7	3.5	5.3	Ω
Turn-on delay time c	t <sub>d(on)</sub>				16	25	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = -15 V, $R_L$ = 0.2 $\Omega$ $I_D$ $\cong$ -100 A, $V_{GEN}$ = -10 V, $R_g$ = 1 $\Omega$		-	204	310	ns
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			1	126	190	
Fall time <sup>c</sup>	t <sub>f</sub>			-	72	110	
Source-Drain Diode Ratings and Characteristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	-300	Α
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> = -30 A, V <sub>GS</sub> = 0 V		-	-0.8	-1.5	V
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -40 A, di/dt = 100 A/μs		-	66	135	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	100	200	nC
Reverse recovery fall time	t <sub>a</sub>			-	31	-	
Reverse recovery rise time	t <sub>b</sub>			-	35	-	ns
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>			-	-3.4	-	Α

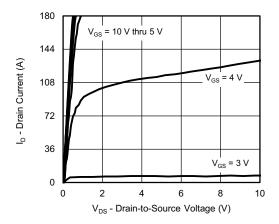
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

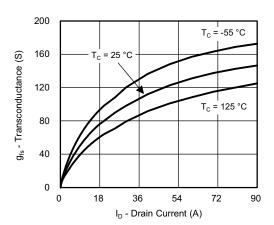
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



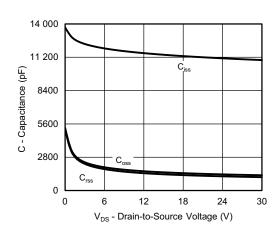
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



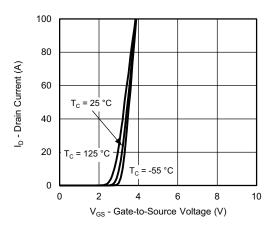
### **Output Characteristics**



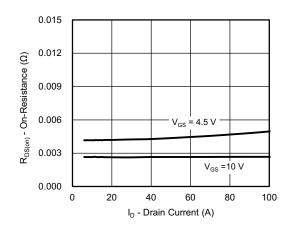
Transconductance



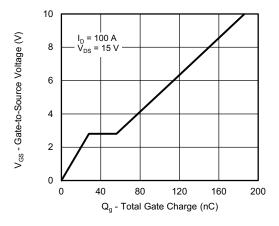
Capacitance



**Transfer Characteristics** 



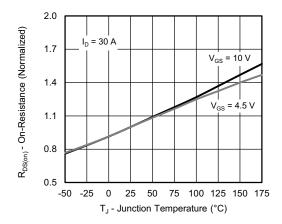
On-Resistance vs. Drain Current



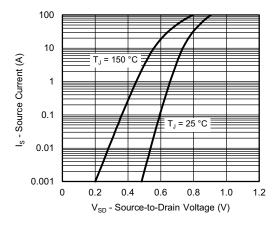
**Gate Charge** 



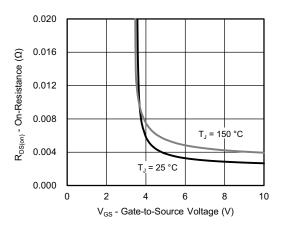
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



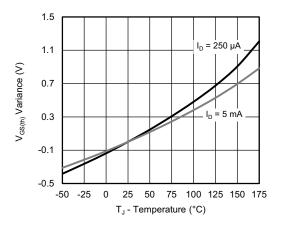
On-Resistance vs. Junction Temperature



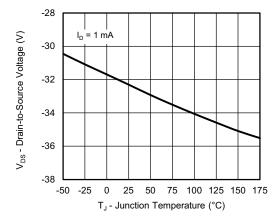
**Source Drain Diode Forward Voltage** 



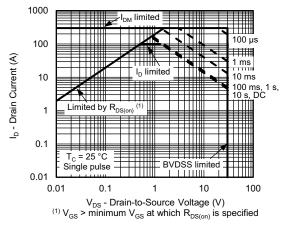
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



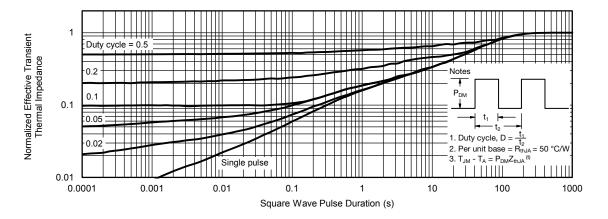
Drain Source Breakdown vs. Junction Temperature



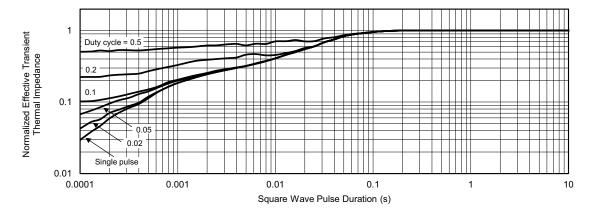
Safe Operating Area



### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

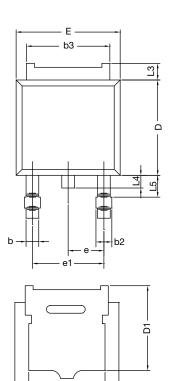
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to- Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

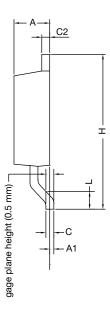
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## **TO-252AA Case Outline**





	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56 BSC		0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019					

### Note

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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